

N-Channel Enhancement Mode Power MOSFET

● Features

VDS	VGS	RDSon TYP	ID
60V	±20V	30mR@10V	9A
		35mR@4V5	

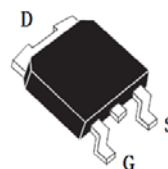
● Applications

- E-tool;
- E-Toy;
- Motor Driver

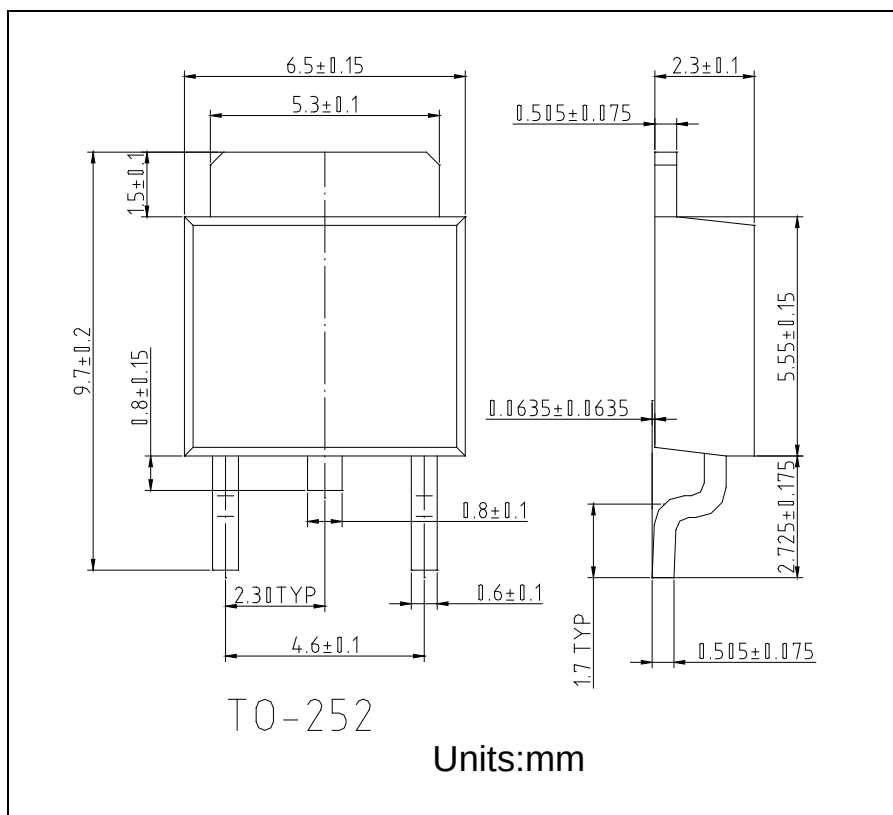
● General Description

SSC8062GT8 uses advanced trench technology to provide excellent $R_{DS(ON)}$. It is particularly suitable for DCDC conversion and motor driver.

● Pin Configuration



● Package Information





SSC8062GT8

● **Absolute Maximum Ratings** @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Parameter		Symbol	Ratings	Unit
Drain-Source Voltage		V_{DSS}	60	V
Gate-Source Voltage		V_{GSS}	± 20	V
Drain Current	Continuous	I_{D}	9	A
	Pulse	I_{DM}	45	
Total Power Dissipation ^(note1)		P_{D}	2.5	W
Operating and Storage Junction Temperature Range		$T_{\text{J}}, T_{\text{STG}}$	-55 to +150	$^\circ\text{C}$

Note1: Surface Mounted on 1in pad area.

● **Electrical Characteristics** @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Parameter ^(note2)	Symbol	Test Conditions	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain–Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 250 uA	60	--	--	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V	--	--	1	uA
Gate–Body Leakage	I _{GSS}	V _{GS} = ± 20 V, V _{DS} = 0 V	--	--	±100	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(TH)}	V _{DS} = V _{GS} , I _D = 250 uA	1	1.4	3	V
Static Drain–Source On–Resistance	R _{DS(ON)}	V _{GS} = 10 V, I _D = 5.5 A	--	30	41	mR
		V _{GS} = 4.5 V, I _D = 4.5 A	--	35	52	
DYNAMIC CHARACTERISTICS						
Input Capacitance	C _{ISS}	V _{DS} = 10 V, V _{GS} = 0 V, F = 1MHz	--	1180	--	pF
Output Capacitance	C _{OSS}		--	170	--	
Reverse Transfer Capacitance	C _{RSS}		--	100	--	
SWITCHING CHARACTERISTICS						
Turn–On Delay Time	T _{D(ON)}	V _{GS} =10V, V _{DS} =30V, R _L =5.4R, R _{GEN} =3R, I _D =5.5A	--	--	25	nS
Turn–On Rise Time	T _R		--	--	70	
Turn–Off Delay Tim	T _{D(OFF)}		--	--	300	
Turn–Off Fall Time	T _F		--	--	150	
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
Diode Forward Voltage	V _{SD}	V _{GS} = 0 V, I _S = 2 A	0.5	0.77	1.0	V

Note2: Short duration test pulse used to minimize self-heating effect.

Typical Performance Characteristics

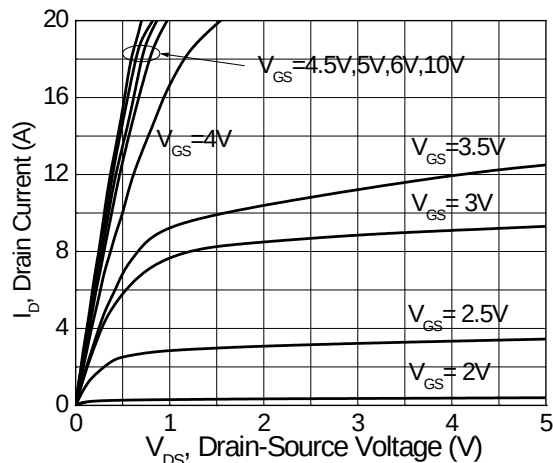


Figure 1. Output Characteristics

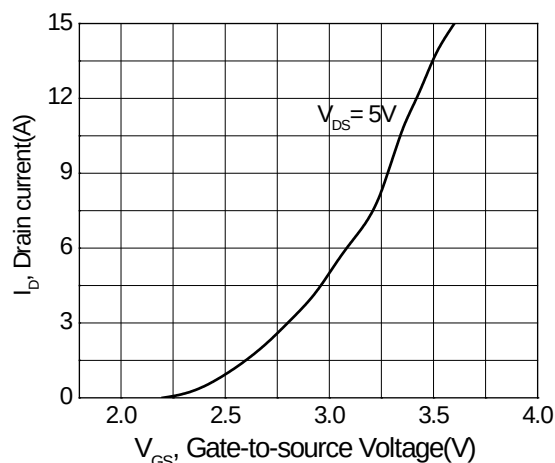


Figure 2. Transfer Characteristics

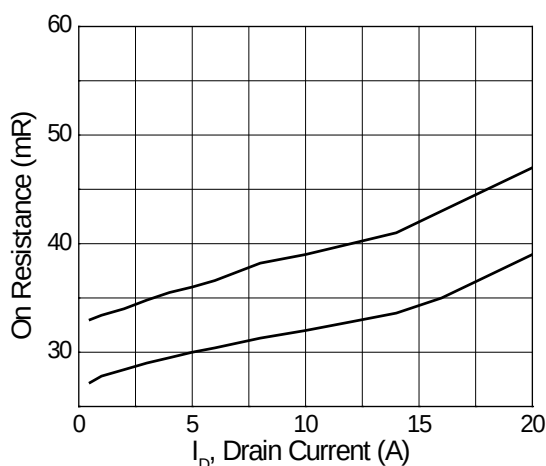


Figure 3. On Resistance

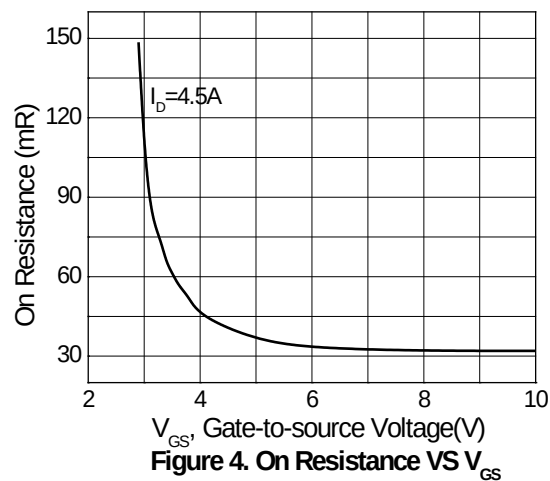


Figure 4. On Resistance VS V_{GS}

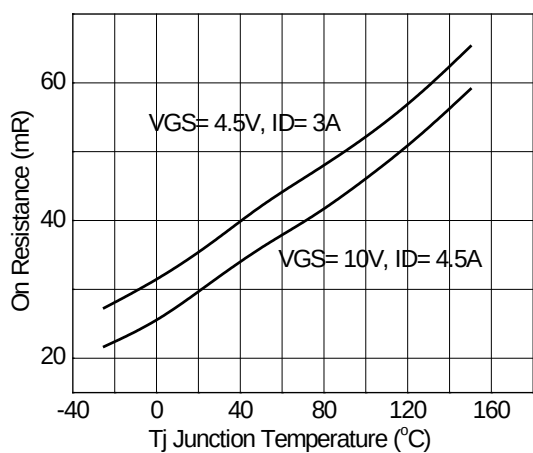


Figure 5 . On resistance vs. Temperature

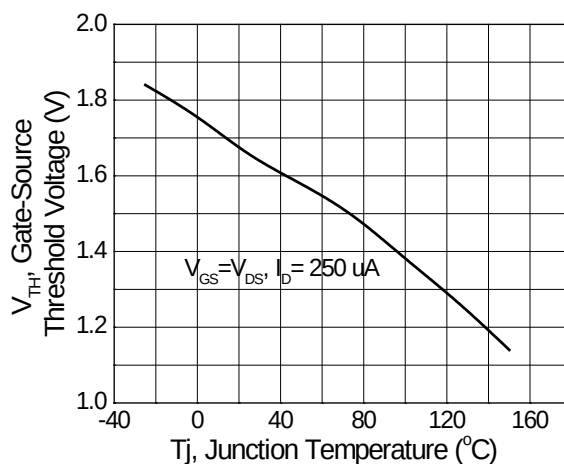


Figure 6. Gate Threshold Vs. Temperature

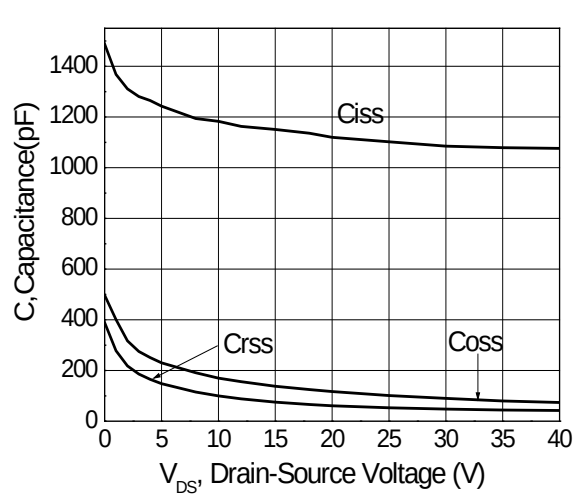


Figure 7. Capacitance

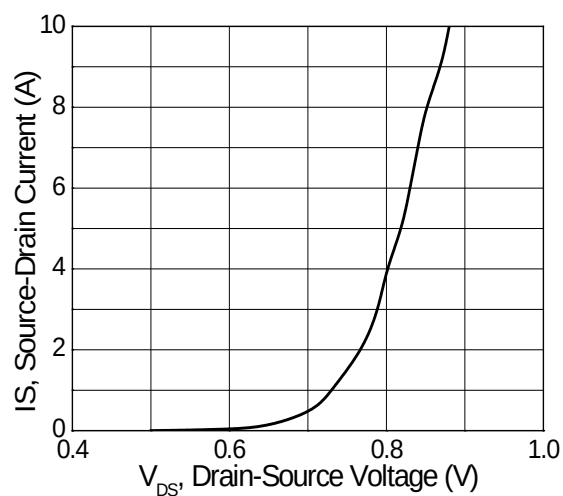


Figure 8. Body Diode Forward Characteristics



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